

High Current Common Mode Choke

FEATURES

- Surface mountable (multiple case sizes), high current common mode choke for DC power line
- Base terminals are treated, allows for easy mounting on PCB
- Paired wire coil for high stability
- Optimized for transmission of high quality signals
- Operating temperature: -40 °C to +85 °C
- Rated Current: Based on temp. rise; ΔT : 40 °C, typical
- Material categorization: For definitions of compliance please see



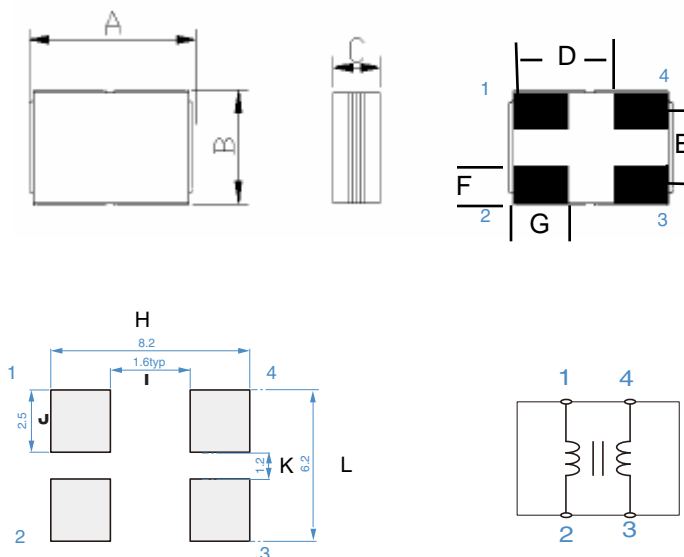
APPLICATIONS

- LAN's, telephones, personal computers
- CD-ROM drives, electronic games
- Other electronic devices

STANDARD ELECTRICAL SPECIFICATIONS					
PART NUMBER	COMMON MODE IMPEDANCE AT 100 MHz (Ω)	RATED VOLTAGE MAX. (V_{DC})	RATED CURRENT MAX. (mA)	DC RESISTANCE MAX. (Ω)	INSULATION RESISTANCE MIN. (M Ω)
CMF2J601WIT	600 \pm 25%	120	3000	0.150	10

Smallest packaging:1500PCS

DIMENSIONS

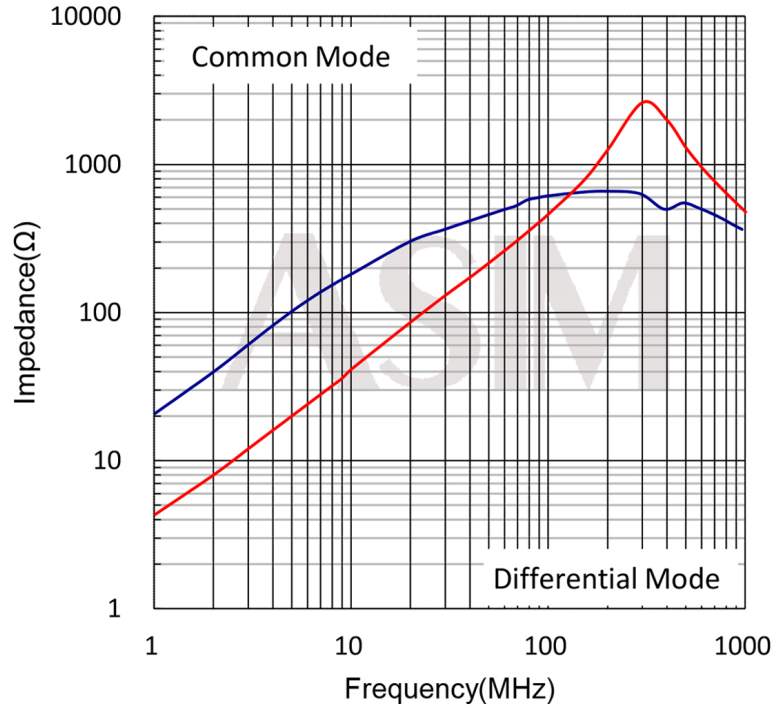


A (mm)	7.6 \pm 1.0
B(mm)	6.0 \pm 1.0
C(mm)	3.2 \pm 1.0
D (mm)	4.8 \pm 1.0
E (mm)	4.2 \pm 1.0
F (mm)	1.8 \pm 1.0
G (mm)	2.8 \pm 1.0

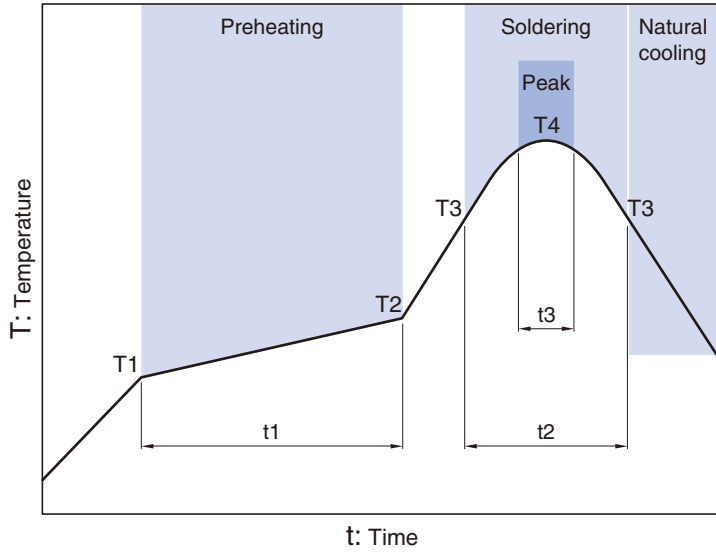
H	I	J	K	L
8.2 \pm 0.2	1.6 TYP	2.5 \pm 0.2	1.2 TYP	6.2 \pm 0.2

Dimensions in mm

PERFORMANCE GRAPHS: INDUCTANCE AND Q VS. FREQUENCY



RECOMMENDED REFLOW PROFILE



Preheating			Soldering		Peak	
Temp.	Temp.	Time	Temp.	Time	Temp.	Time
T1	T2	t1	T3	t2	T4	t3
150°C	180°C	60 to 120s	230°C	25 to 35s	250°C	5s

RELIABILITY TEST METHOD

◆ ELECTRIC

NO.	Test items	Standard	Experiment Method
1	Temperature characteristics	$\Delta L/L \ 20^{\circ}\text{C} \leq \pm 10\%$	The test should be done after the sample has stabilized in the ring The temperature of the product is -40 to $+125^{\circ}\text{C}$, and the L (ΔL) value of the product is the same as the original L value. Suitable for normal temperature and humidity should be $\Delta L / L \ 20^{\circ}\text{C} \leq \pm 10\%$.
2	Load test	The product must not have any damage, such as smoke or sparks	1.2 times the rated current, the time is 5 minutes

6.2 ENVIRONMENTAL CHARACTERISTICS

NO.	Test items	Standard	Experiment Method								
1	Reflow soldering	Do not have any damage or problems	<p>Reflow of temperature distribution Before the heat: 150-180 °C, Times 60 to 120sec Peak temperature: 250 ± 5 °C, Times 5 sec Hold temperature: 230 ± 5 °C, Times 30 ± 5 sec</p>								
2	Solderability	Welding area of more than 90%	The solder surface is immersed in flux and then immersed in a furnace at 235 ± 5 °C for 5 seconds								
3	Low temperature storage	$\Delta L / L_0 \leq \pm 10\%$, there should be no mechanical damage	The sample should be left for 96 ± 4 hours at a temperature of -40 ± 3 °C and returned to the normal temperature range of 1 hour after completion of the test.) 90-95%.								
4	High temperature storage	$\Delta L / L_0 \leq \pm 10\%$, there should be no mechanical damage	The sample should be left for 96 ± 4 hours at a temperature of 125 ± 3 °C. The test should be carried out after returning to normal temperature range for 1 hour.								
5	Constant hot and humid	$\Delta L / L_0 \leq \pm 10\%$, there should be no mechanical damage.	Samples should be left for 96 ± 4 hours at 60 ± 2 °C and 90 °C to 90% humidity (RH). The test is resumed after 1 hour in the normal temperature range.								
6	Temperature cycle	1, no visible mechanical damage. 2, the value of change is less than 10%. 3, the resistance value of less than 5%	In the -25 °C to +85 °C between the respective keep 15min, transit time ≤1min, the number of cycles 5 times, recovery time: 24h test finished (recovery time at least 4h)								
7	vibration	$\Delta L / L_0 \leq \pm 10\%$ There should be no mechanical damage	The sample should be soldered to the printed circuit board When the vibration has an amplitude and 1.5 mm Frequency from 10-55Hz / 1 minute, repeated should be applied to three directions (X, Y, Z) for 2 hours, a total of 6 hours								
8	Impact resistance (MIL-STD-202G Method 213B)	Change in inductance: within ± 10% DC resistance change: ± 10% within the appearance of no obvious abnormalities, should not have mechanical damage.	<p>The test sample shall be soldered to the test substrate by reflow soldering. Then, follow the following test conditions.</p> <table border="1"> <thead> <tr> <th>Pulse</th> <th>Half sine shock</th> </tr> </thead> <tbody> <tr> <td>Acceleration</td> <td>980 m/s²(100g)</td> </tr> <tr> <td>Nominal pulse duration</td> <td>6 ms</td> </tr> <tr> <td>Speed change</td> <td>3.75 m/s</td> </tr> </tbody> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	Pulse	Half sine shock	Acceleration	980 m/s ² (100g)	Nominal pulse duration	6 ms	Speed change	3.75 m/s
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9	Thermal shock (MIL-STD-202G Method 107G)	<p>Change in inductance: within $\pm 10\%$</p> <p>DC resistance change: $\pm 10\%$ within the appearance of no obvious abnormalities, should not have mechanical damage.</p>	<p>The test sample shall be soldered to the test substrate by reflow soldering. Test sample according to the specified time Are placed at a specific temperature, as shown in the table below, from step 1 to step 4.</p> <table border="1" data-bbox="797 327 1453 478"> <thead> <tr> <th colspan="3">1 cycle condition</th> </tr> <tr> <th>Step</th> <th>Temperature ($^{\circ}\text{C}$)</th> <th>Time (minute)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-55 ± 3</td> <td>30 ± 3</td> </tr> <tr> <td>2</td> <td>Room temperature</td> <td>3 or less</td> </tr> <tr> <td>3</td> <td>-125 ± 3</td> <td>30 ± 3</td> </tr> <tr> <td>4</td> <td>Room temperature</td> <td>3 or less</td> </tr> </tbody> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	1 cycle condition			Step	Temperature ($^{\circ}\text{C}$)	Time (minute)	1	-55 ± 3	30 ± 3	2	Room temperature	3 or less	3	-125 ± 3	30 ± 3	4	Room temperature	3 or less
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10	Wet heat resistance (MIL-STD-202G Method 106G)	<p>Change in inductance: within $\pm 10\%$</p> <p>DC resistance change: $\pm 10\%$ within the appearance of no obvious abnormalities, should not have mechanical damage.</p>	<p>The test sample shall be soldered to the test substrate by reflow soldering. Test samples must be placed in a constant temperature and humidity box, according to the table specified temperature and humidity, do not pass the current test.</p> <table border="1" data-bbox="837 722 1409 800"> <tbody> <tr> <td>Temperature</td> <td>$65 \pm 2^{\circ}\text{C}$</td> </tr> <tr> <td>Humidity</td> <td>$90\% \pm 10\% \text{RH}$</td> </tr> <tr> <td>Time</td> <td>500 ± 24 hours</td> </tr> </tbody> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	Temperature	$65 \pm 2^{\circ}\text{C}$	Humidity	$90\% \pm 10\% \text{RH}$	Time	500 ± 24 hours												
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11	Low temperature life (IEC68-2-1Ad)	<p>Change in inductance: within $\pm 10\%$</p> <p>DC resistance change: $\pm 10\%$ within the appearance of no obvious abnormalities, should not have mechanical damage.</p>	<p>The test sample shall be soldered to the test substrate by reflow soldering. The test sample should then be placed in the test conditions as shown in the table below.</p> <table border="1" data-bbox="837 1043 1409 1096"> <tbody> <tr> <td>Temperature</td> <td>$-40 \pm 3^{\circ}\text{C}$</td> </tr> <tr> <td>Time</td> <td>500 ± 24 hours</td> </tr> </tbody> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	Temperature	$-40 \pm 3^{\circ}\text{C}$	Time	500 ± 24 hours														
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12	Low temperature load life (IEC68-2-1Ad)	<p>Change in inductance: within $\pm 10\%$</p> <p>DC resistance change: $\pm 10\%$ within the appearance of no obvious abnormalities, should not have mechanical damage.</p>	<p>The test sample shall be soldered to the test substrate by reflow soldering. The</p> <table border="1" data-bbox="837 1314 1409 1417"> <tbody> <tr> <td>Temperature</td> <td>$-55 \pm 2^{\circ}\text{C}$</td> </tr> <tr> <td>Plus load current</td> <td>Rated current</td> </tr> <tr> <td>Time</td> <td>500 ± 24 hours</td> </tr> <tr> <td>Hourly power time</td> <td>3/4 power 1/4 power off</td> </tr> </tbody> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	Temperature	$-55 \pm 2^{\circ}\text{C}$	Plus load current	Rated current	Time	500 ± 24 hours	Hourly power time	3/4 power 1/4 power off										
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13	Damp heat load (MIL-STD-202G Method 108A)	<p>Change in inductance: within $\pm 10\%$</p> <p>DC resistance change: $\pm 10\%$ within the appearance of no obvious abnormalities, should not have mechanical damage.</p>	<p>The test sample shall be soldered to the test substrate by reflow soldering. Test samples shall be placed in a constant temperature and humidity box, according to the table specified in the temperature and humidity under the continuous access to the rated current for testing.</p> <table border="1" data-bbox="837 1696 1409 1774"> <tbody> <tr> <td>Temperature</td> <td>$60 \pm 2^{\circ}\text{C}$</td> </tr> <tr> <td>Humidity</td> <td>90~95%RH</td> </tr> <tr> <td>Time</td> <td>500 ± 24 hours</td> </tr> </tbody> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	Temperature	$60 \pm 2^{\circ}\text{C}$	Humidity	90~95%RH	Time	500 ± 24 hours												
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14	High temperature life test (IEC68-2-2Ba)	<p>Change in inductance: within $\pm 10\%$</p> <p>DC resistance change: $\pm 10\%$ within the appearance of no obvious abnormalities, should not have mechanical damage.</p>	<p>The test sample shall be soldered to the test substrate by reflow soldering.</p> <p>The test sample shall be placed in a constant temperature and humidity tank and the current shall not be supplied at the temperature specified in the table.</p> <table border="1" data-bbox="841 348 1411 401"> <tr> <td>Temperature</td> <td>$125 \pm 3^\circ\text{C}$</td> </tr> <tr> <td>Time</td> <td>500 ± 24 hours</td> </tr> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	Temperature	$125 \pm 3^\circ\text{C}$	Time	500 ± 24 hours				
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15	High temperature load life test (MIL-STD-202G Method 108A)	<p>Change in inductance: within $\pm 10\%$</p> <p>DC resistance change: $\pm 10\%$ within the appearance of no obvious abnormalities, should not have mechanical damage.</p>	<p>The test sample shall be soldered to the test substrate by reflow soldering. The</p> <table border="1" data-bbox="841 611 1411 711"> <tr> <td>Temperature</td> <td>$85 \pm 2^\circ\text{C}$</td> </tr> <tr> <td>Plus load current</td> <td>Rated current</td> </tr> <tr> <td>Time</td> <td>2000 ± 24 hours</td> </tr> <tr> <td>Hourly power time</td> <td>3/4 power 1/4 power off</td> </tr> </table> <p>Recovery: 2 hours of recovery in standard condition and subsequent testing within 48 hours.</p>	Temperature	$85 \pm 2^\circ\text{C}$	Plus load current	Rated current	Time	2000 ± 24 hours	Hourly power time	3/4 power 1/4 power off
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